

Fig. 1
(PRIOR ART)

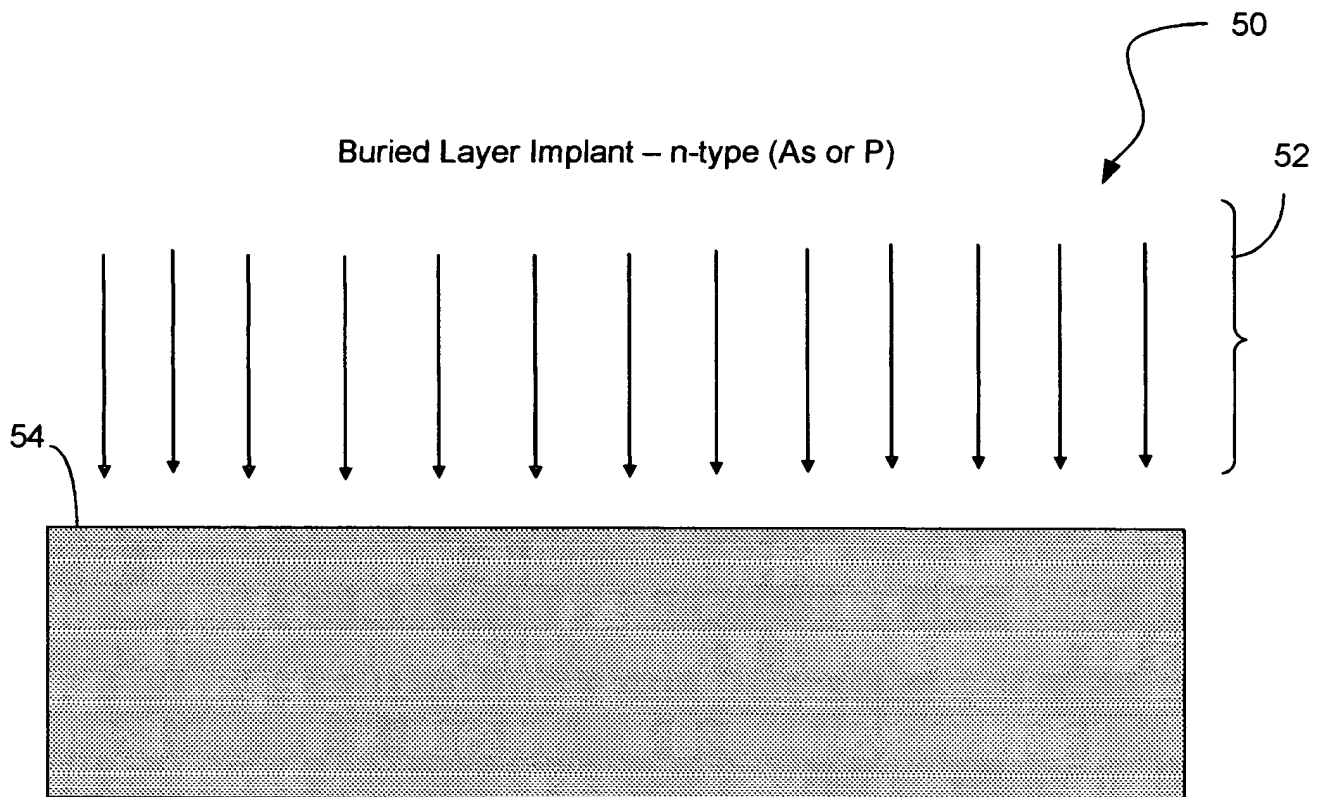


Fig. 2

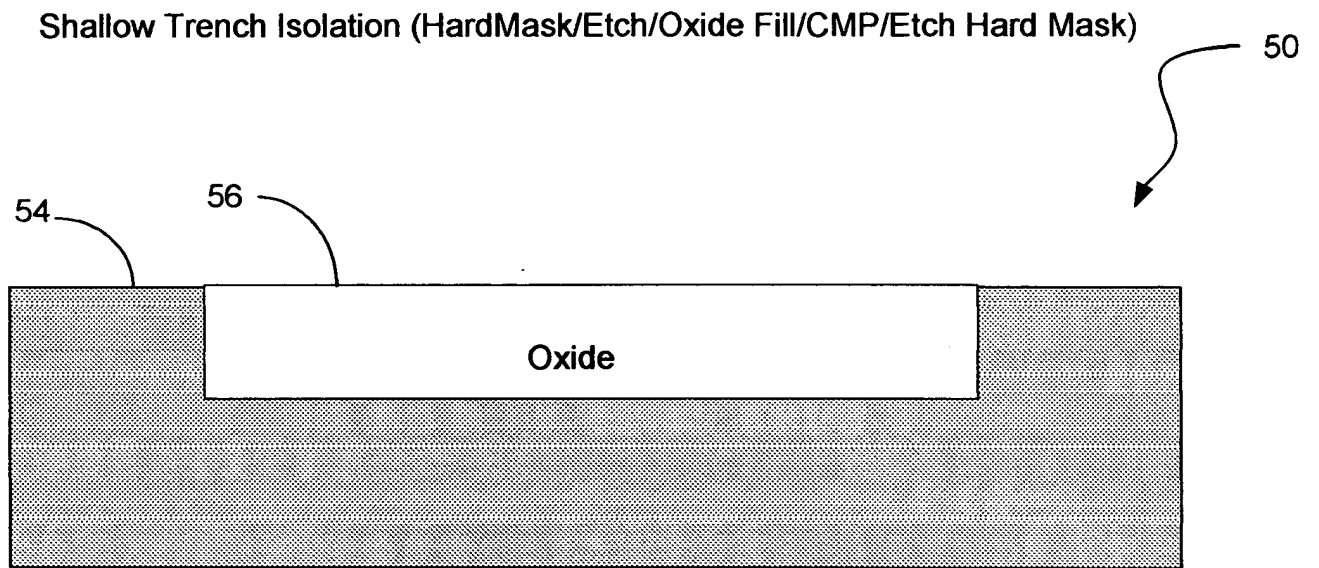


Fig. 3

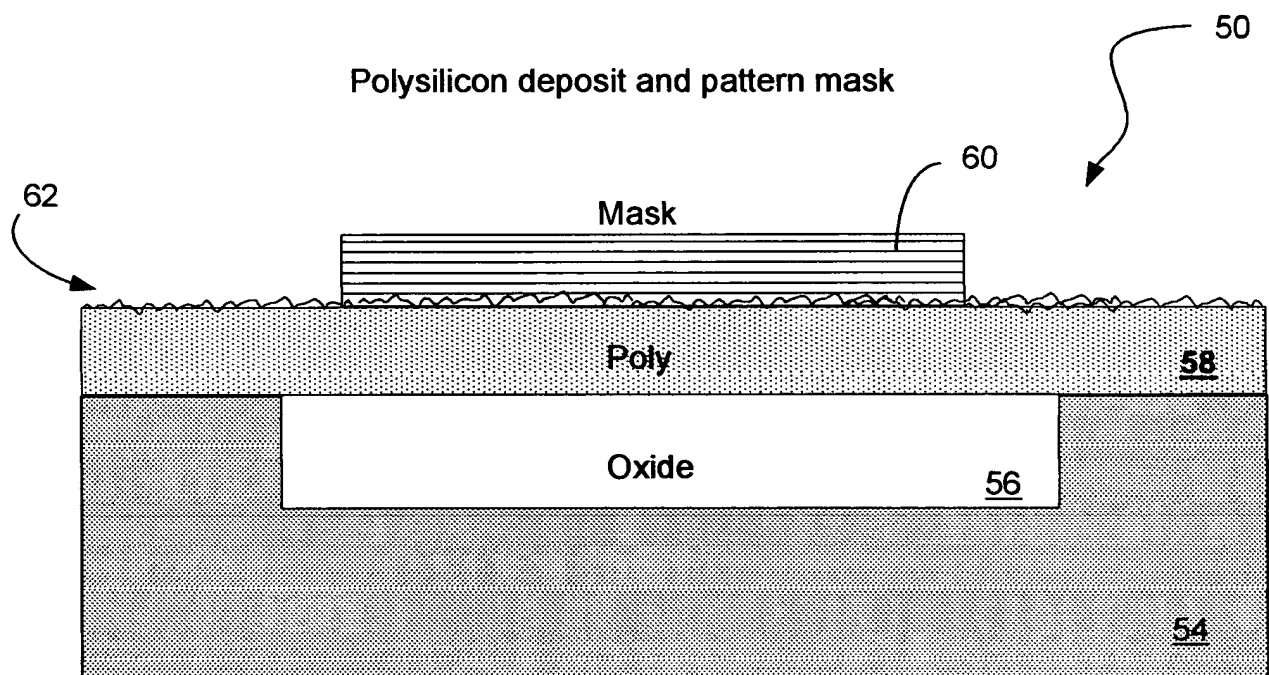


Fig. 4

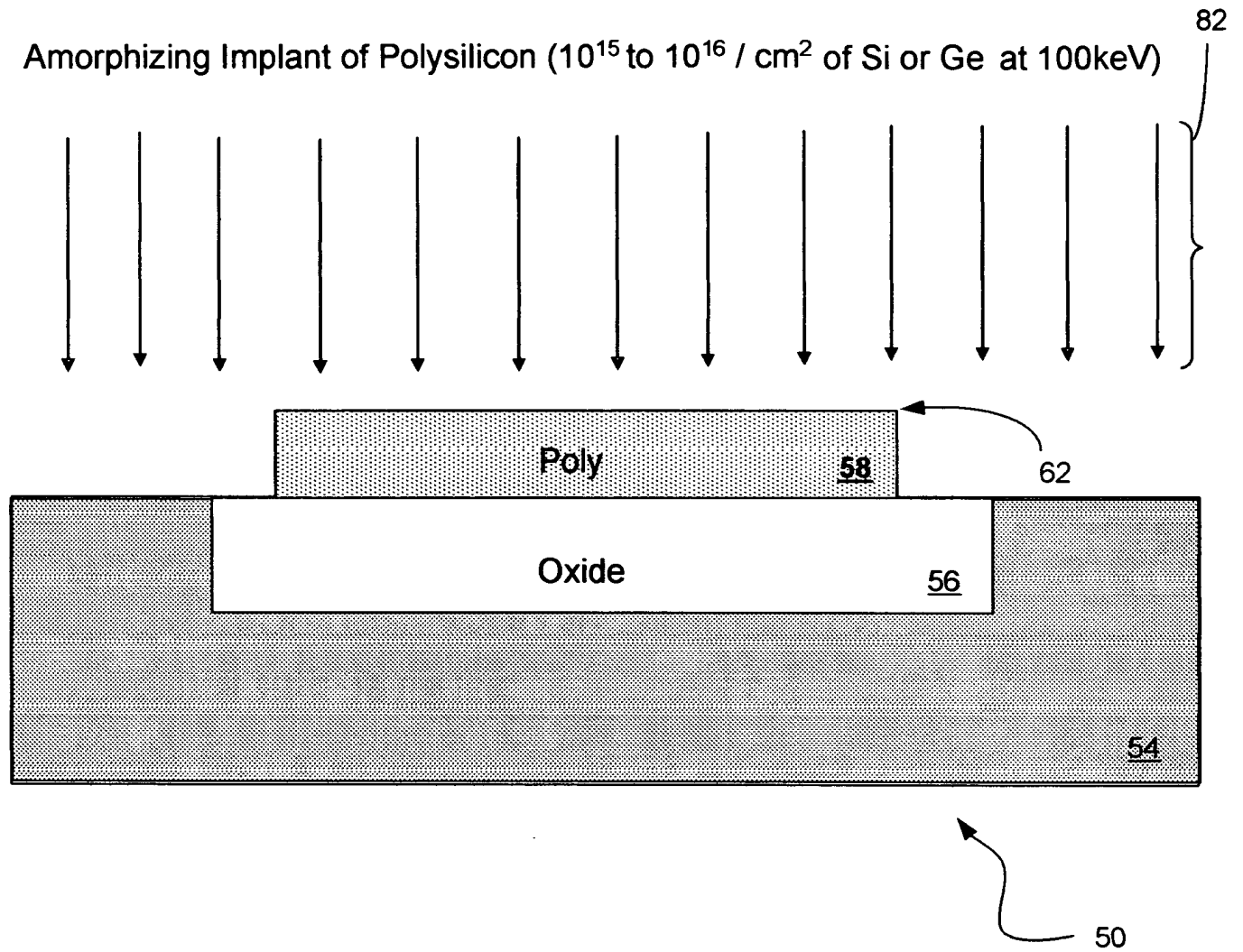


Fig. 5

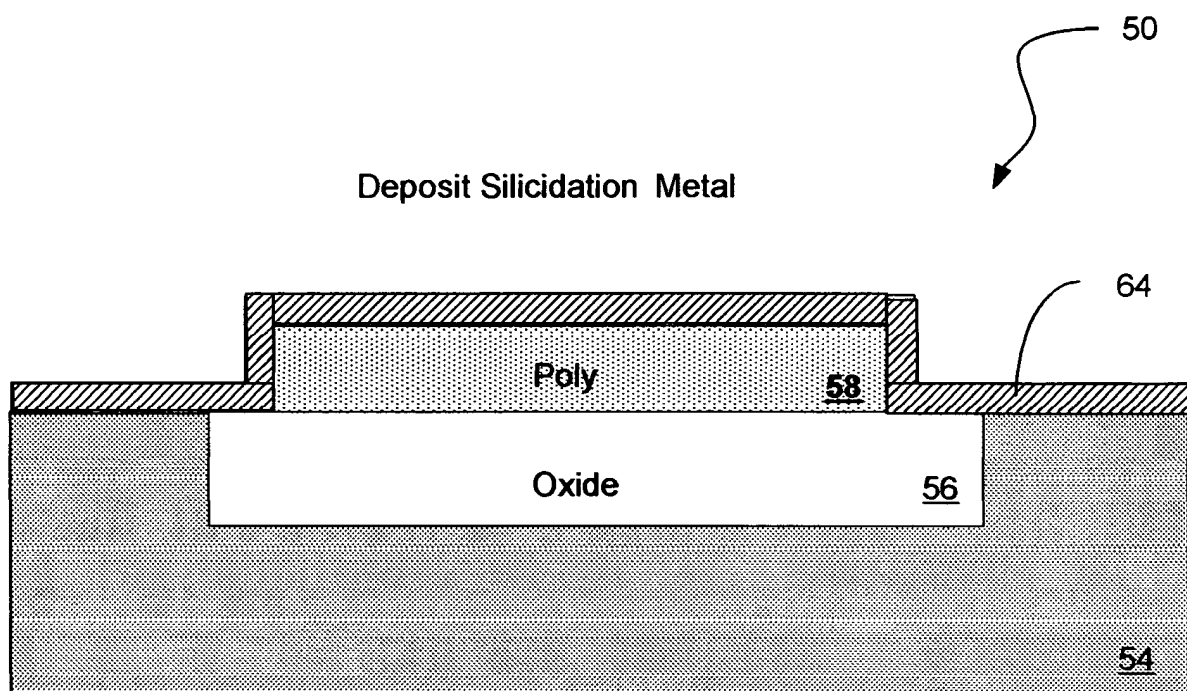


Fig. 6a

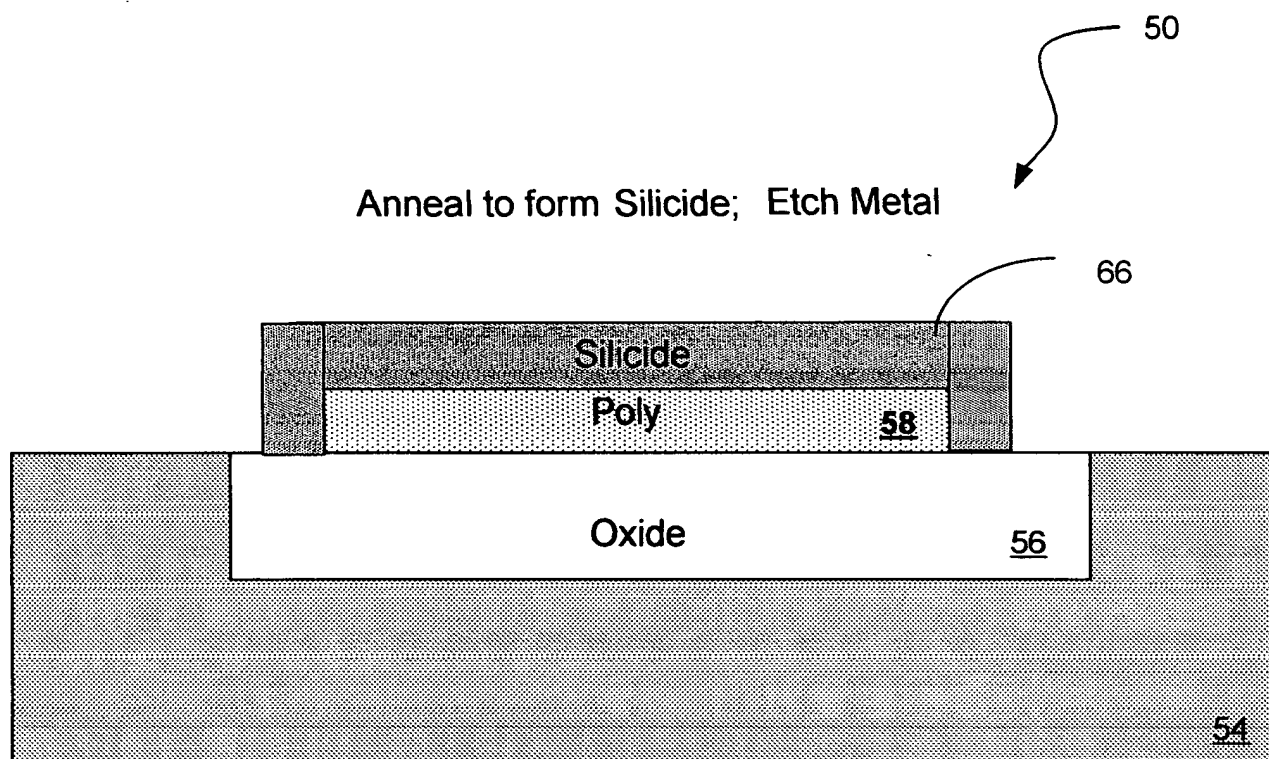


Fig. 6b

Deposit Dielectric Layer (Oxide or Nitride 500 to 5000 Angstroms)

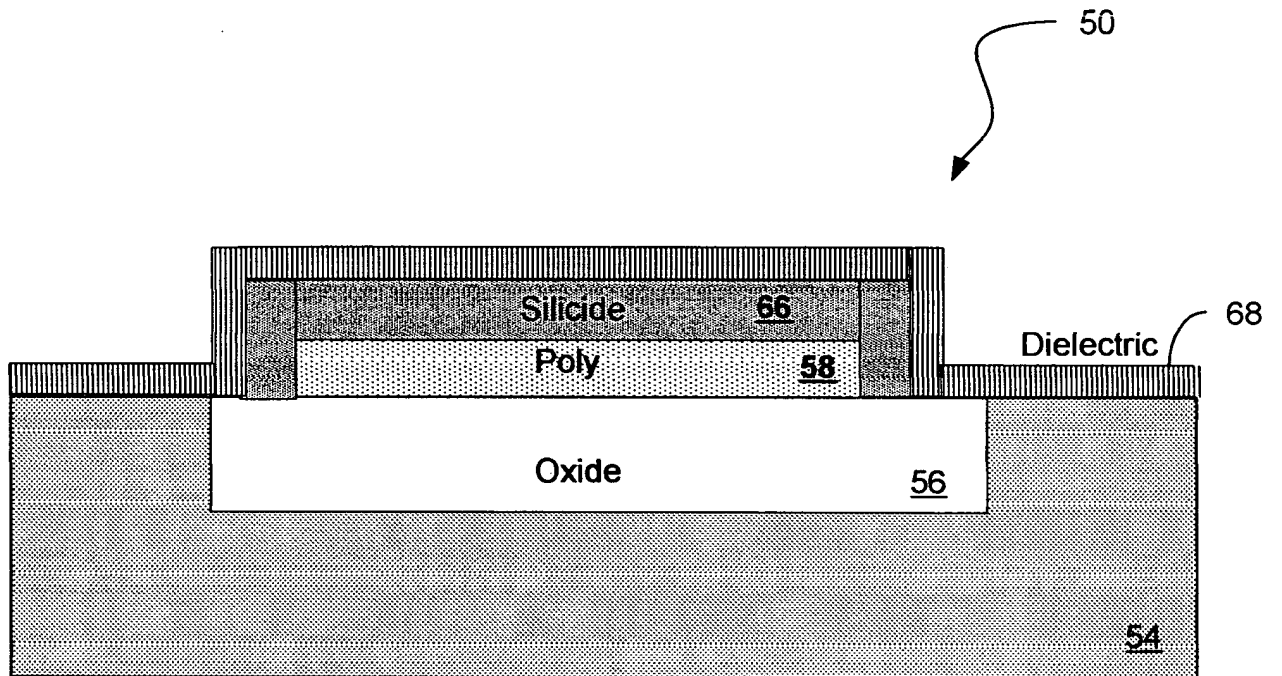


Fig. 7

Deposit Top Metal Plate (Aluminum/Copper with TiN Barrier Layer);
Mask and Etch Capacitor Metal

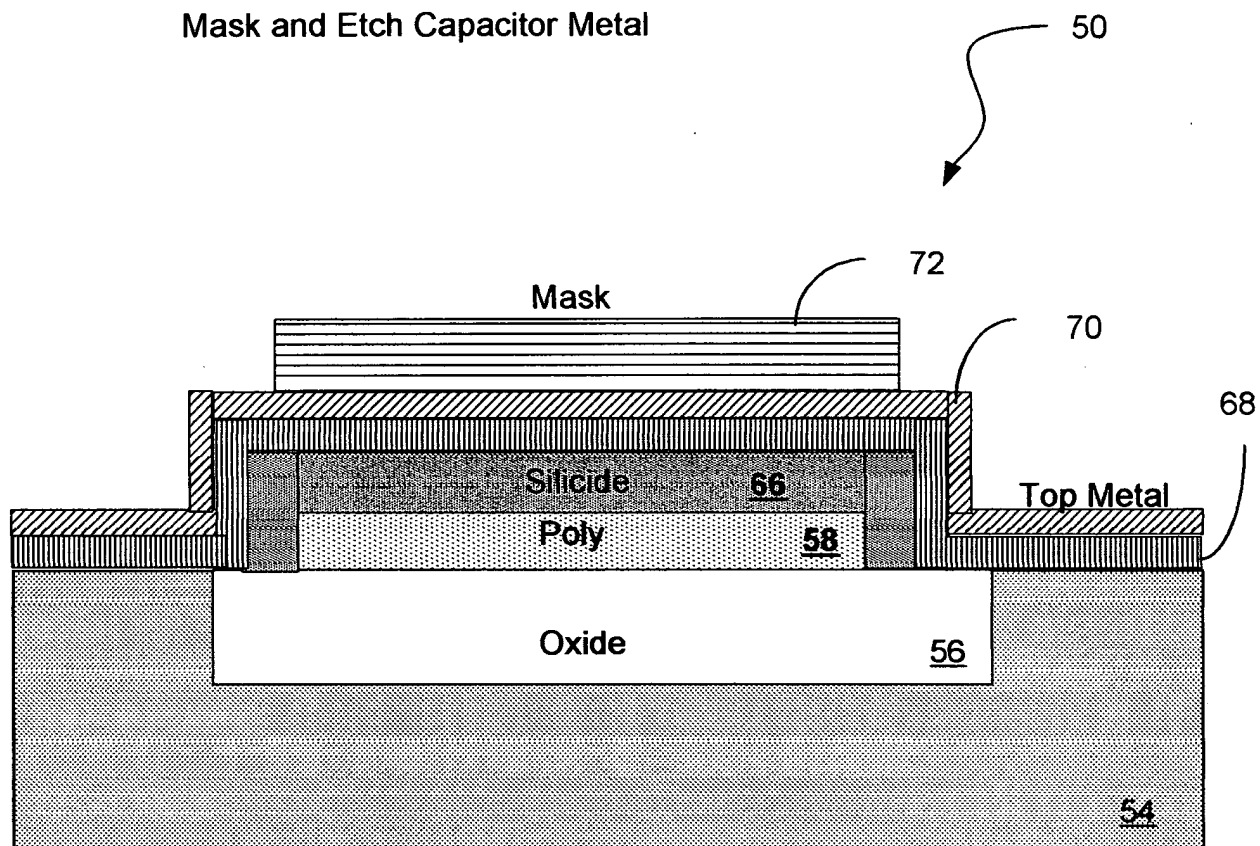


Fig. 8

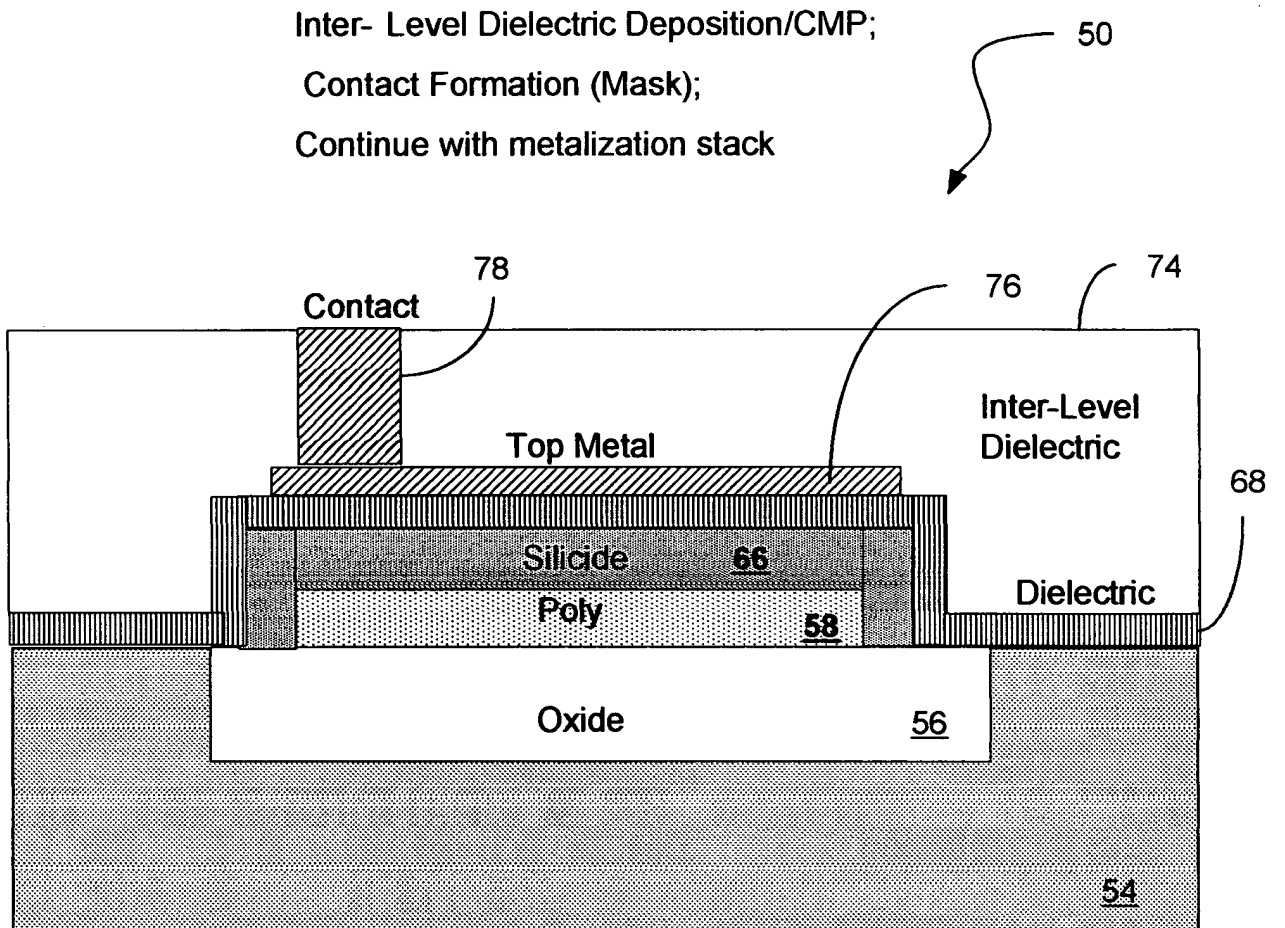


Fig. 9

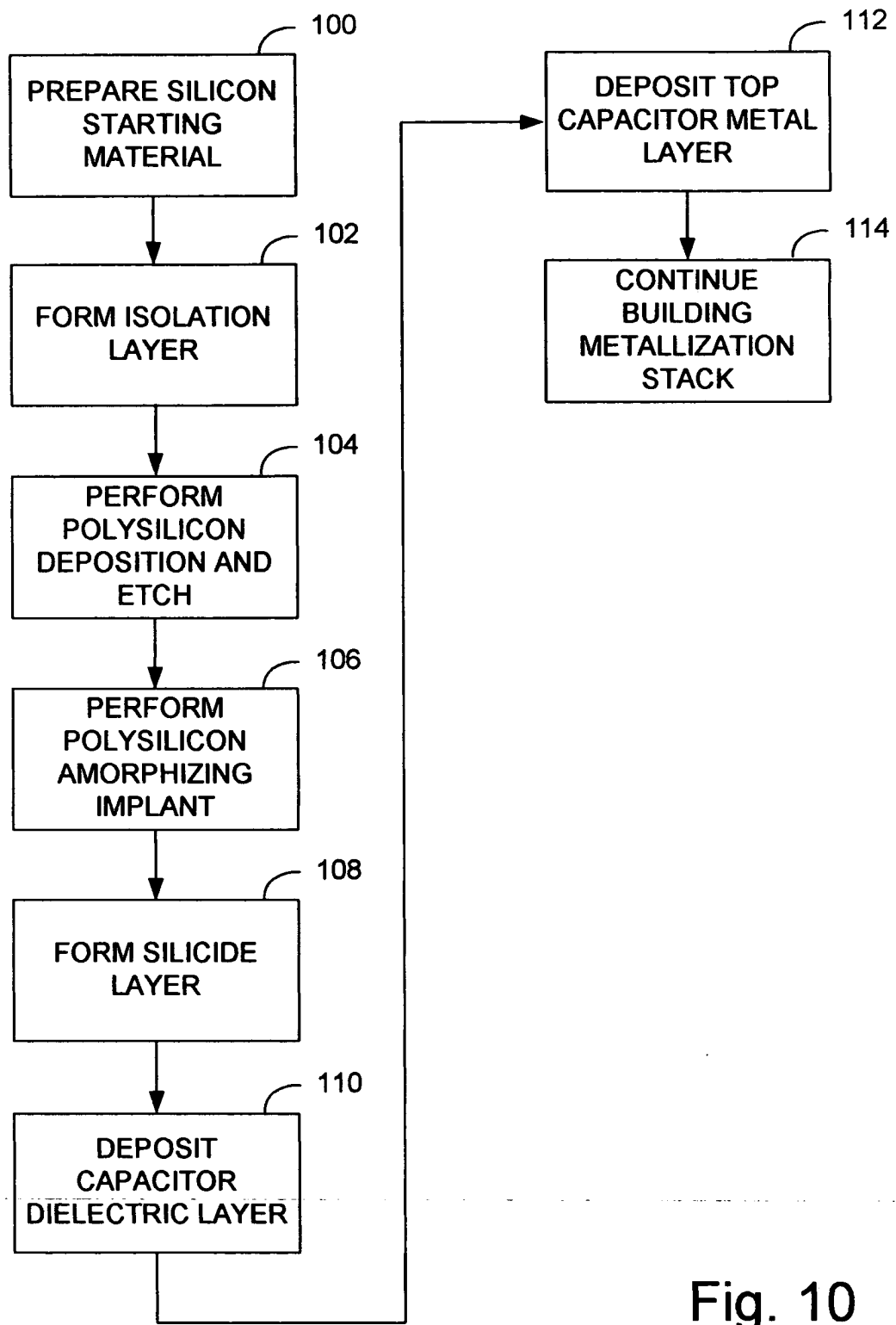


Fig. 10